

## Update on Investigations at Cambridge

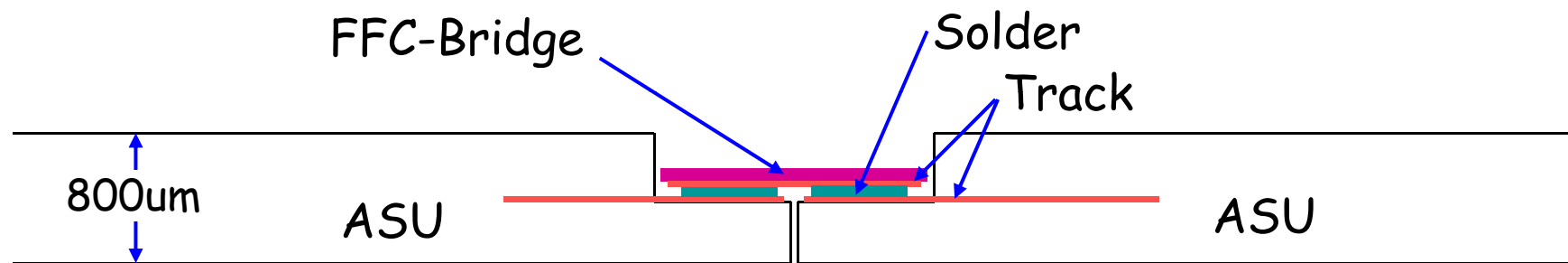
- Recap
- Lines of Enquiry
- Bits and Boards
- Where we are

We have been looking at using "Bridges" to jumper multiple connections between adjacent ASUs

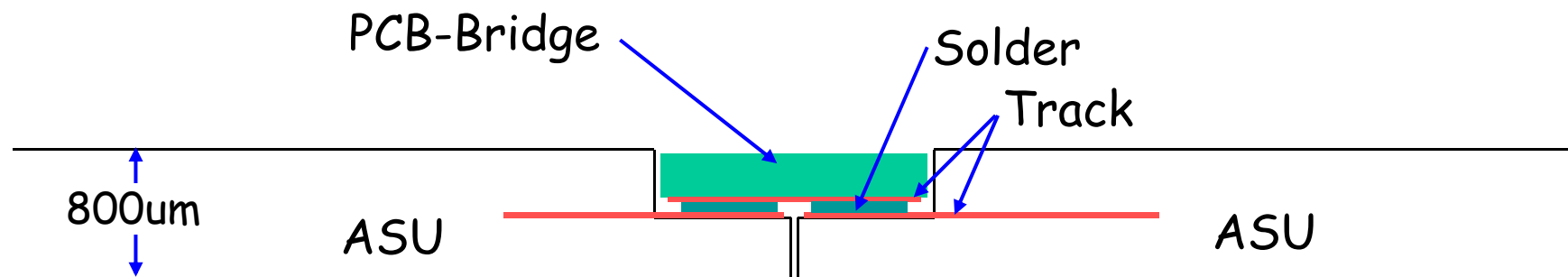
The Bridge would be soldered onto pads on the ASU (or DIF) PCB

Each Bridge would provide  $\geq 30$  connections  
Up to 4 Bridges fit in the width of an ASU  
... 1 per path would be an ideal solution 😊😊

Short FFC (Flat, Flexible-Cable) Bridges make connections on a 1mm pitch - OK for at least 120 connections



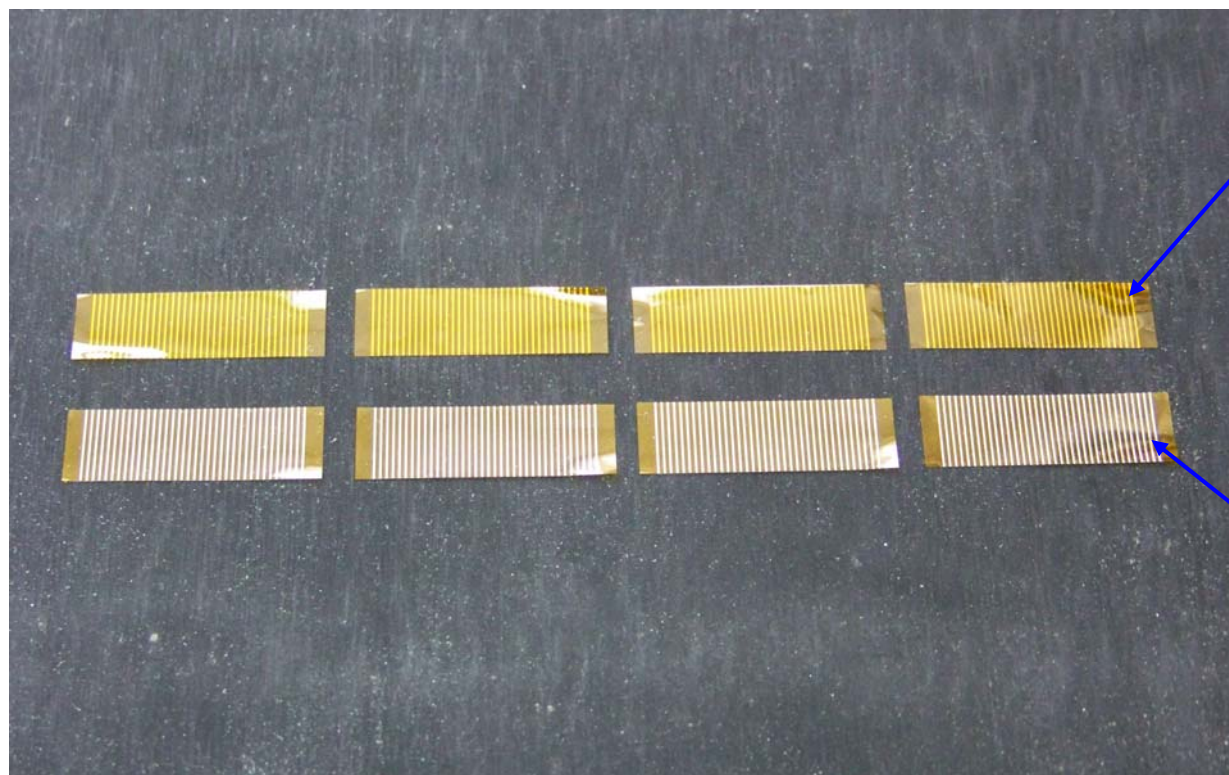
Alternatively the Bridges can be thin PCBs, also with 1mm pitch connections. This gives a mechanical as well as electrical joint



- Provides copious connections (4 x 30 across ASU)
  - plenty for Power Planes
  - would allow 4 or more rows of connections
- Solder joints well proven electrically
- Signal transmission likely to be less compromised
- Rework possible

- Using an FFC-Bridge would make the mechanical joint independent: this might appeal to the mechanical designers
- Using a PCB-Bridge combines mechanical and electrical joint

- How to solder the joints
  - IR using linear Quartz-Halogen lamp
  - Laser Soldering
- Signal Integrity
  - Signal delivery along LVDS lines
  - Crosstalk
- Effect on Detector Glue Connections
  - Does soldering cause joint deterioration?
  - If not, what about rework?



Top View

Thin traces on  
Kapton backing

Under View

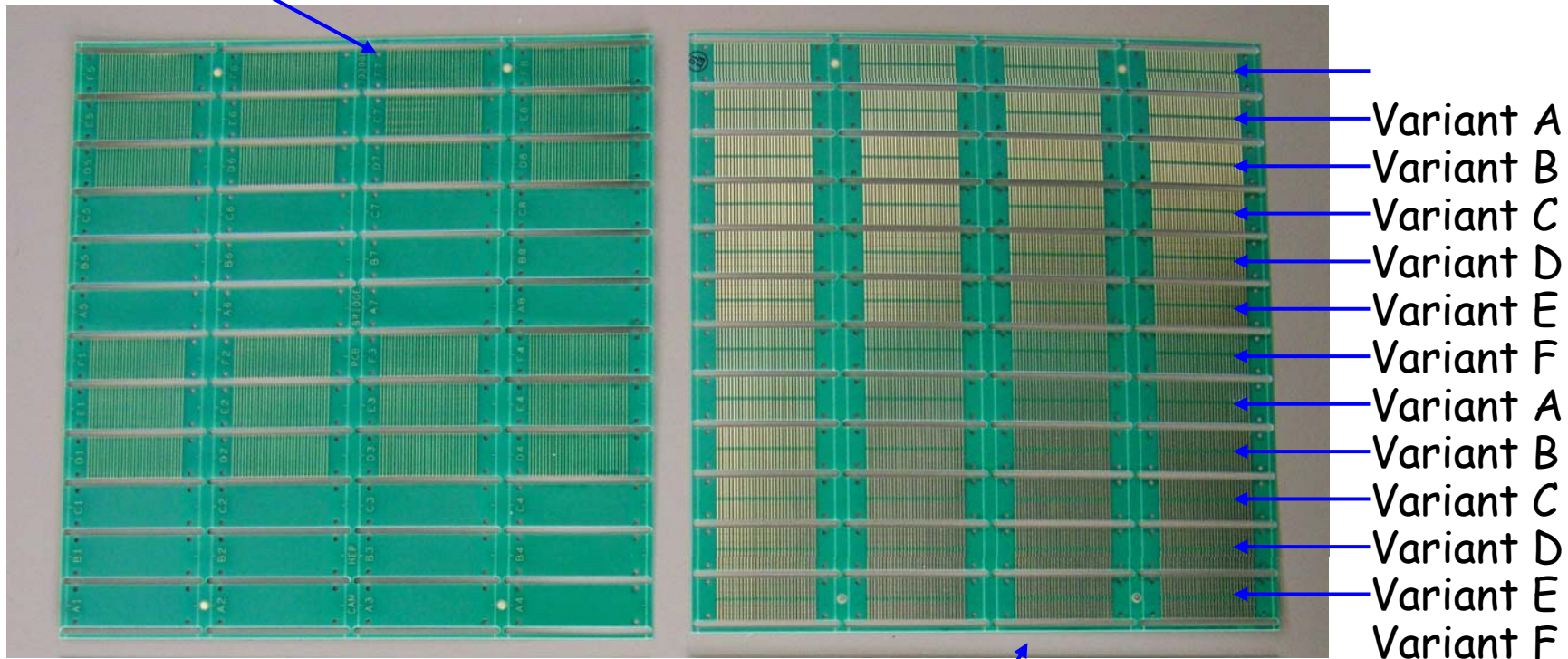
**FFC-Bridges:** we have 250 cut, 250 on roll

We now cut them in half: only ~6 mm long



# ECAL SLAB Interconnect - Bits

Top View



0.4 mm FR4, Au Plated

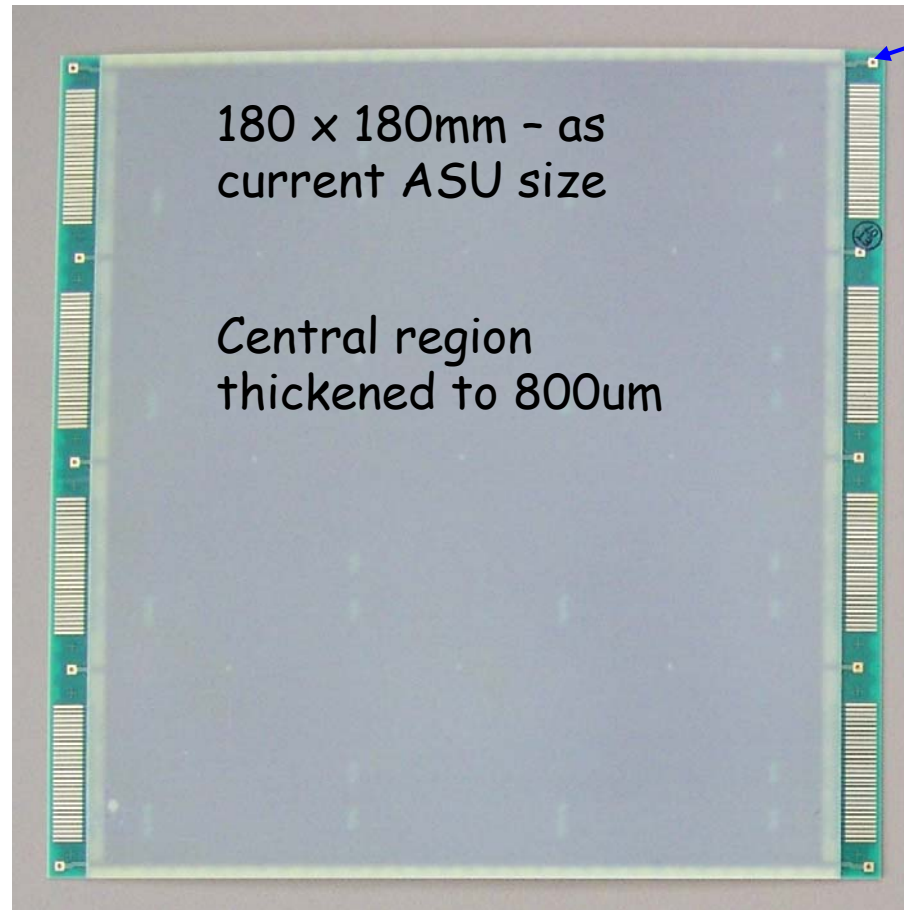
Under View

**PCB-Bridges:** have 15 Panels of 8 lots of 6 variants

We cut these in half too: only ~6 mm long

## ECAL SLAB Interconnect - PCBs

### Top View



4 identical rows of differential  
tracks connecting 36 way  
interconnect pads on left and right

Can be sliced into 4 sections, so  
provides for many trials

Differential tracks have a range of  
spacings & other characteristics to  
test signal propagation and cross-  
talk

ASU-Test\_2 PCB: we have 15



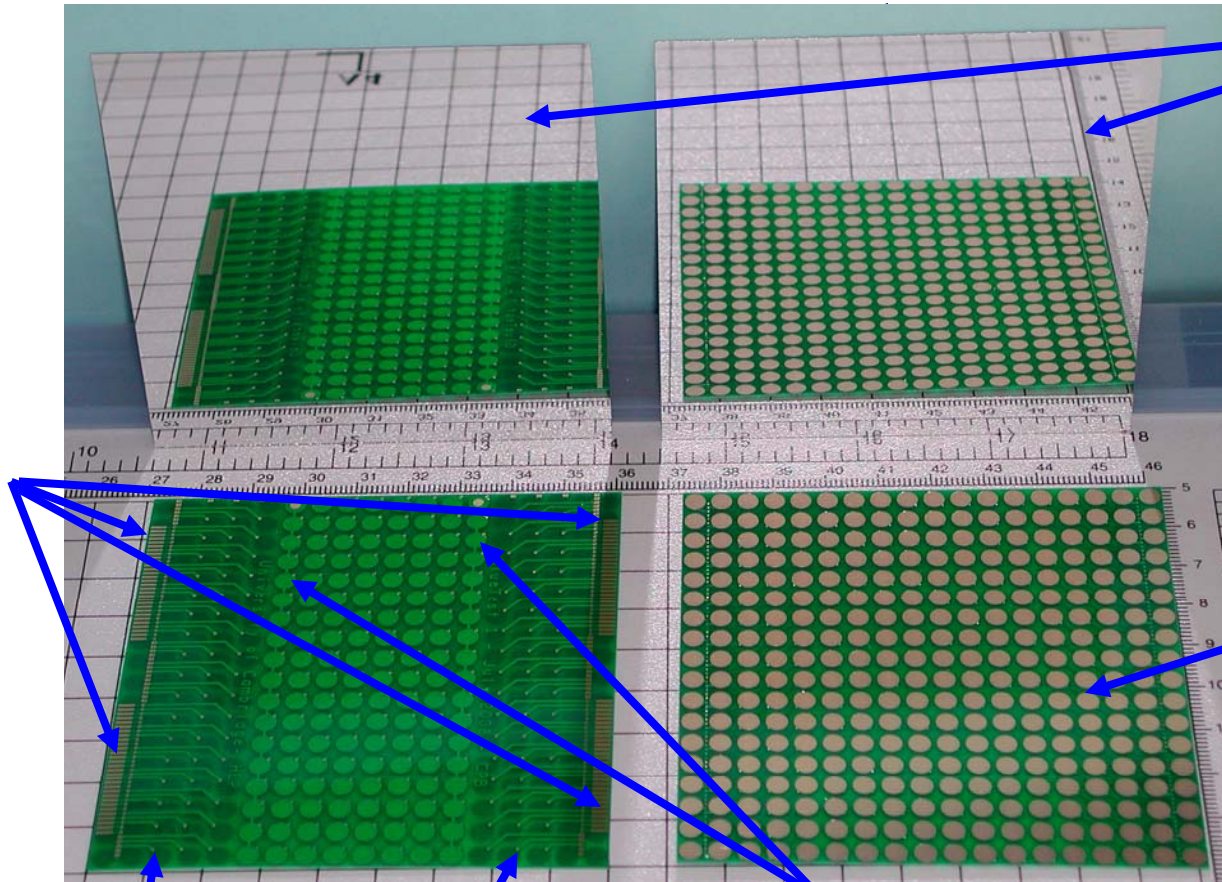
# ECAL SLAB Interconnect - PCBs

Top View

Under View

Aluminised 300um Glass plates: we have 9 (plus more un-coated)

30-way Interconnect Footprints (4 per PCB)



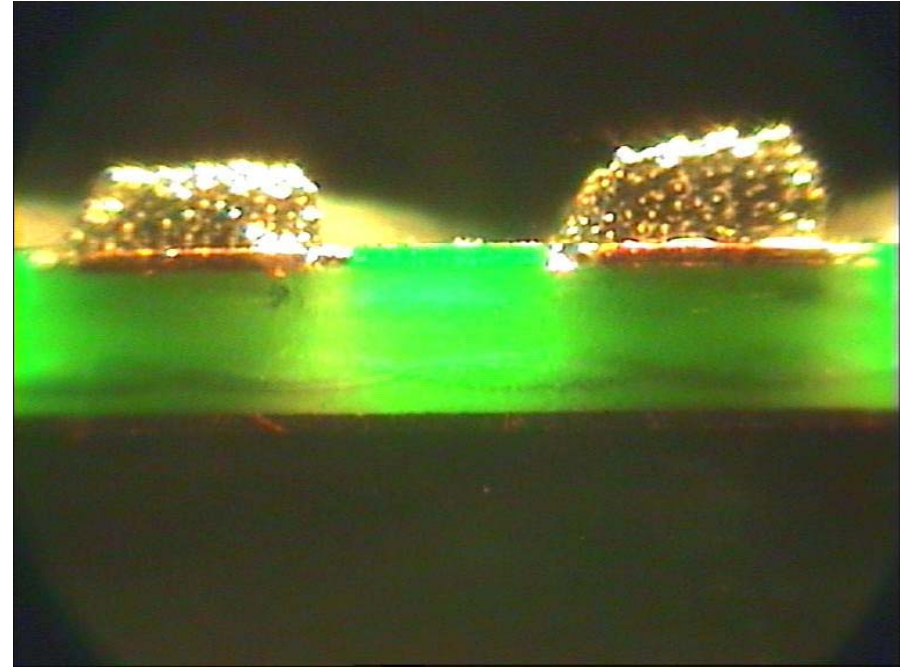
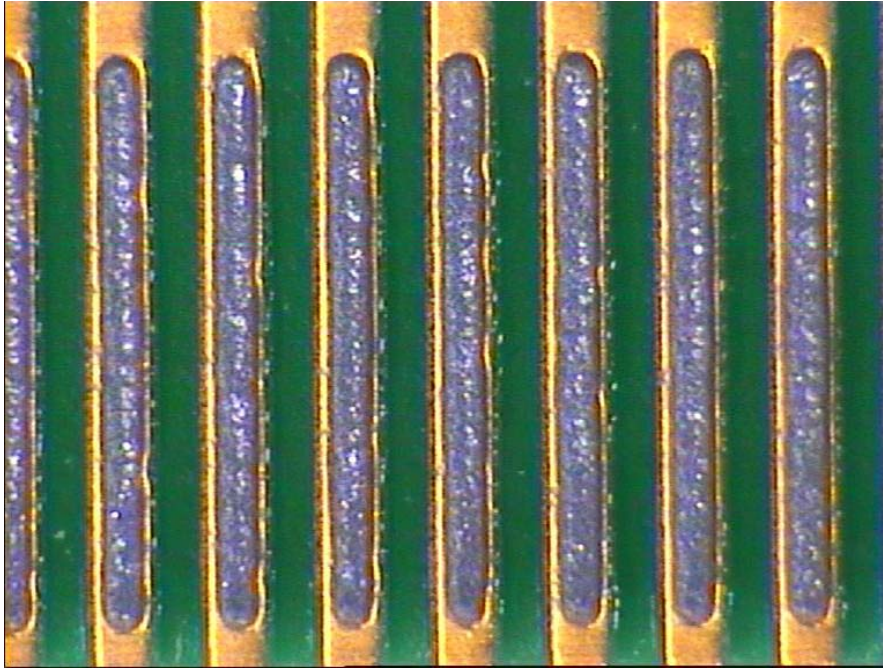
Pads on 5mm pitch

5 rows joined to fingers/pads

These 2 rows "commoned"

## GlueTest PCB: we have 28

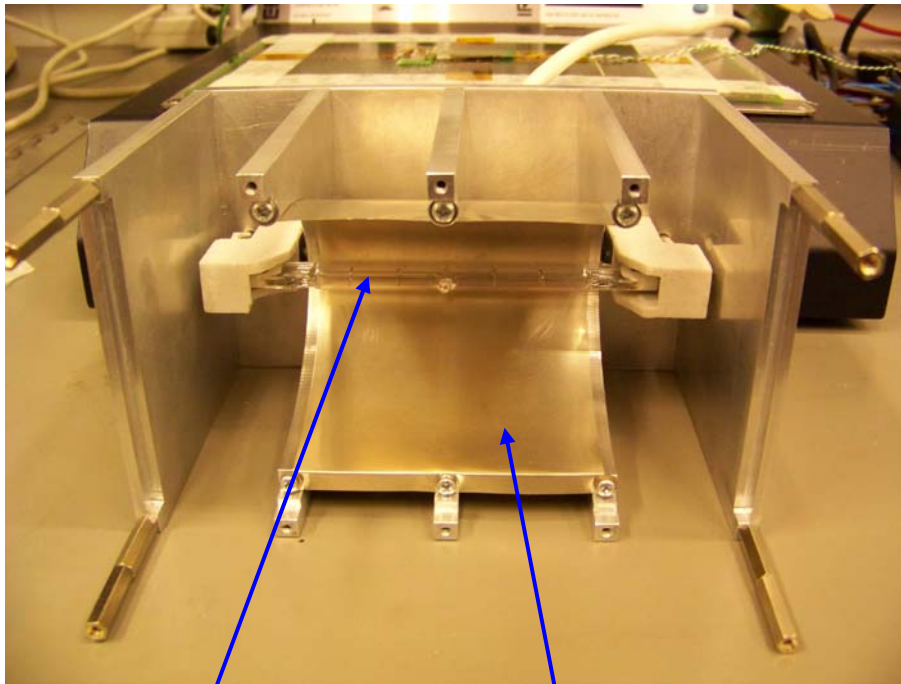
## ECAL SLAB Interconnect - **Soldering**



**PCB-Bridges:** solder pasting



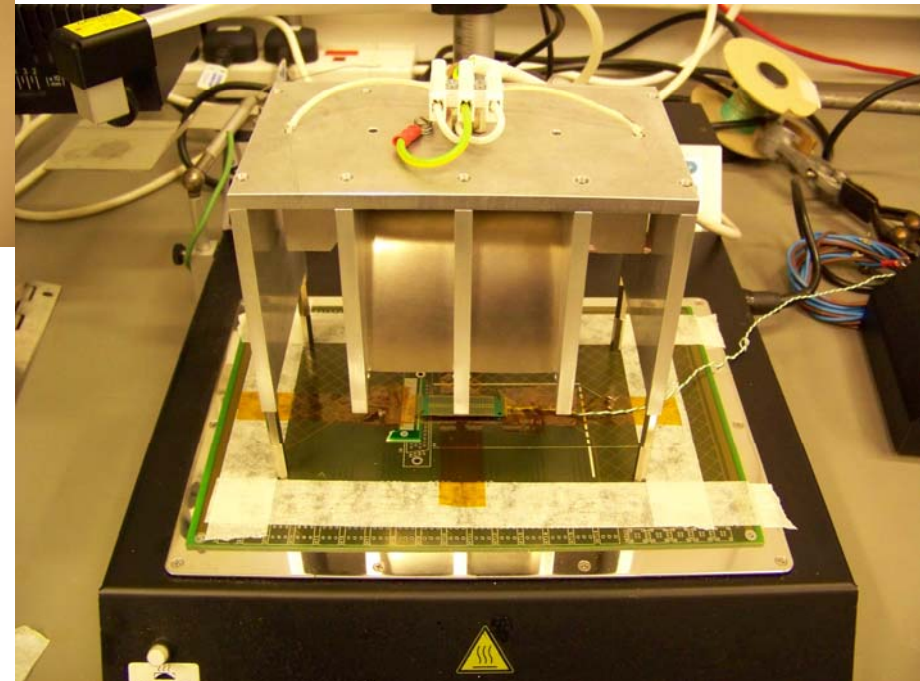
# ECAL SLAB Interconnect - **Soldering**



Linear Halogen Lamp

Elliptical Reflector

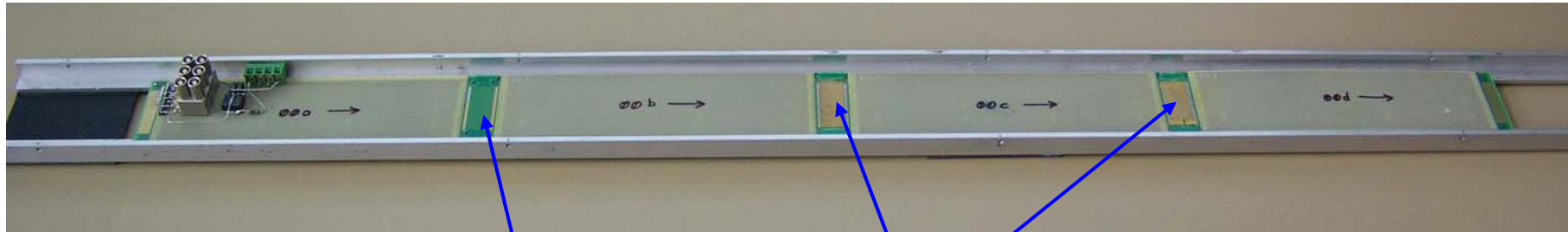
## Re-flowing a PCB-Bridge



# Imaging Halogen IR Source

Maurice Goodrick & Bart Hommels , University of Cambridge

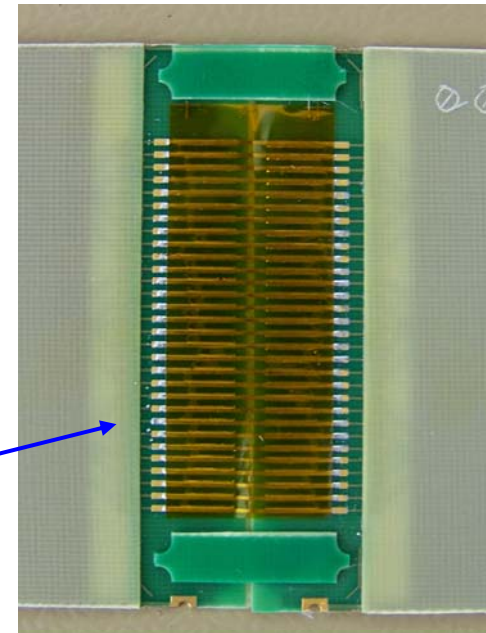
## 4 Section ASU-Test Assembly



PCB-Bridge joint

FFC-Bridge joints

View of FFC-Bridge joint



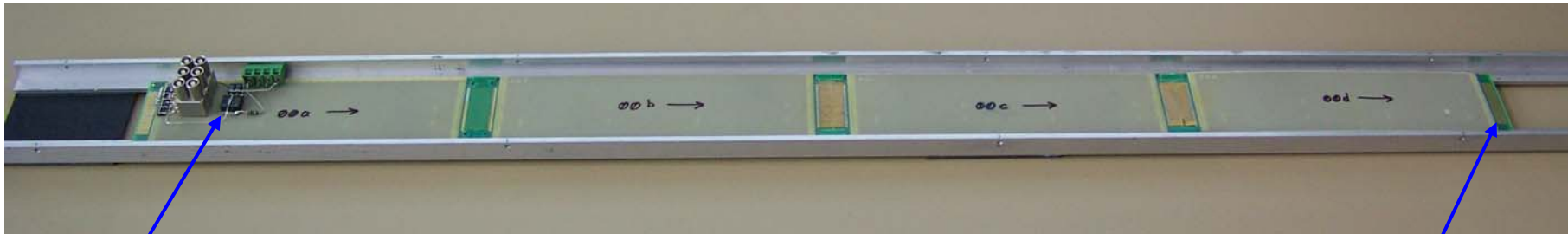
**ASU-Test\_2: 4 Section Assembly**

# ECAL SLAB Interconnect - **Soldering**



**ASU-Test\_2: 10 Section Assembly in Progress**

Using the 4 Section ASU-Test\_2 Assembly



LVDS Drive Circuit:  
Back Term'n = 100R

Track Series Res  $\sim 8R$

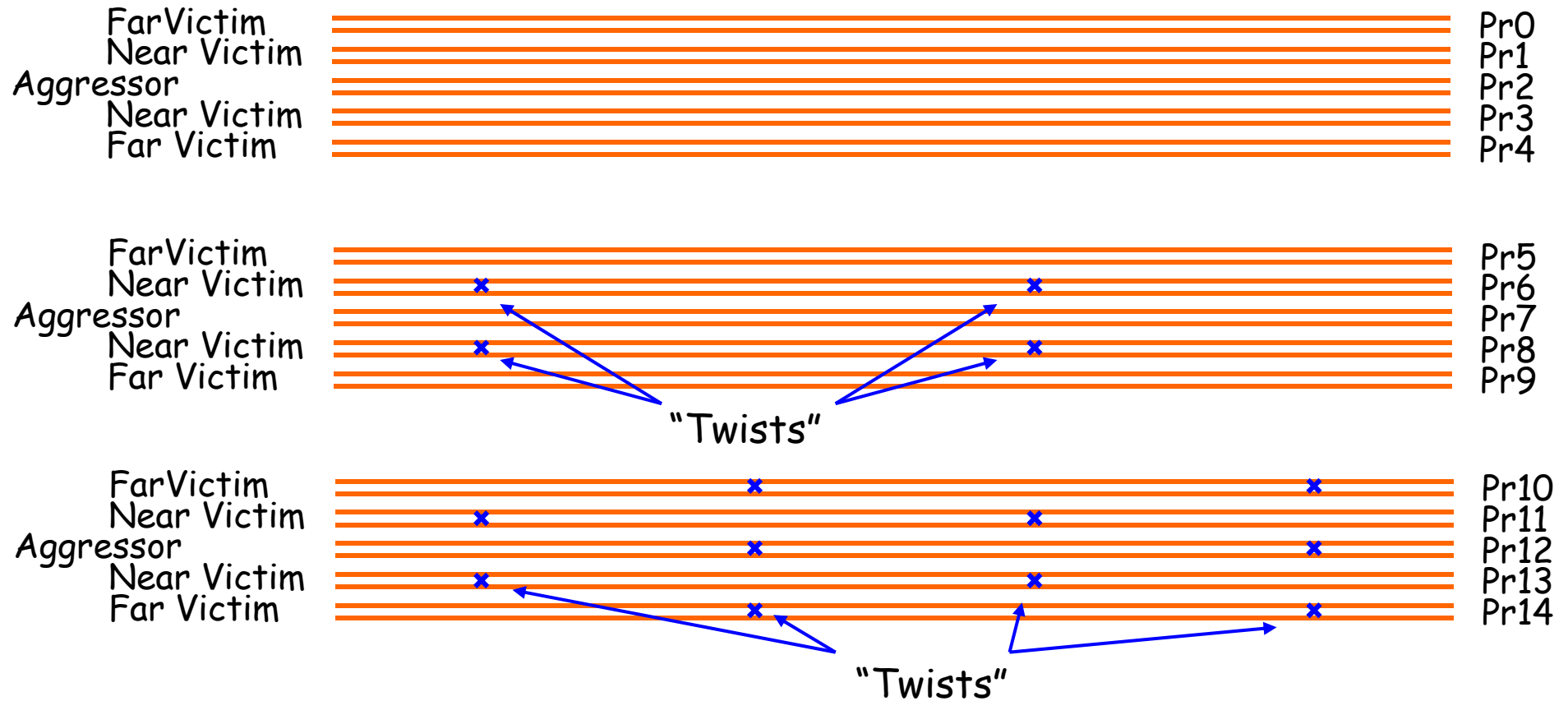
End Term'n = 82R

Length =  $4 \times 180\text{mm} = 720\text{mm}$

## Crosstalk Setup



# ECAL SLAB Interconnect - Crosstalk

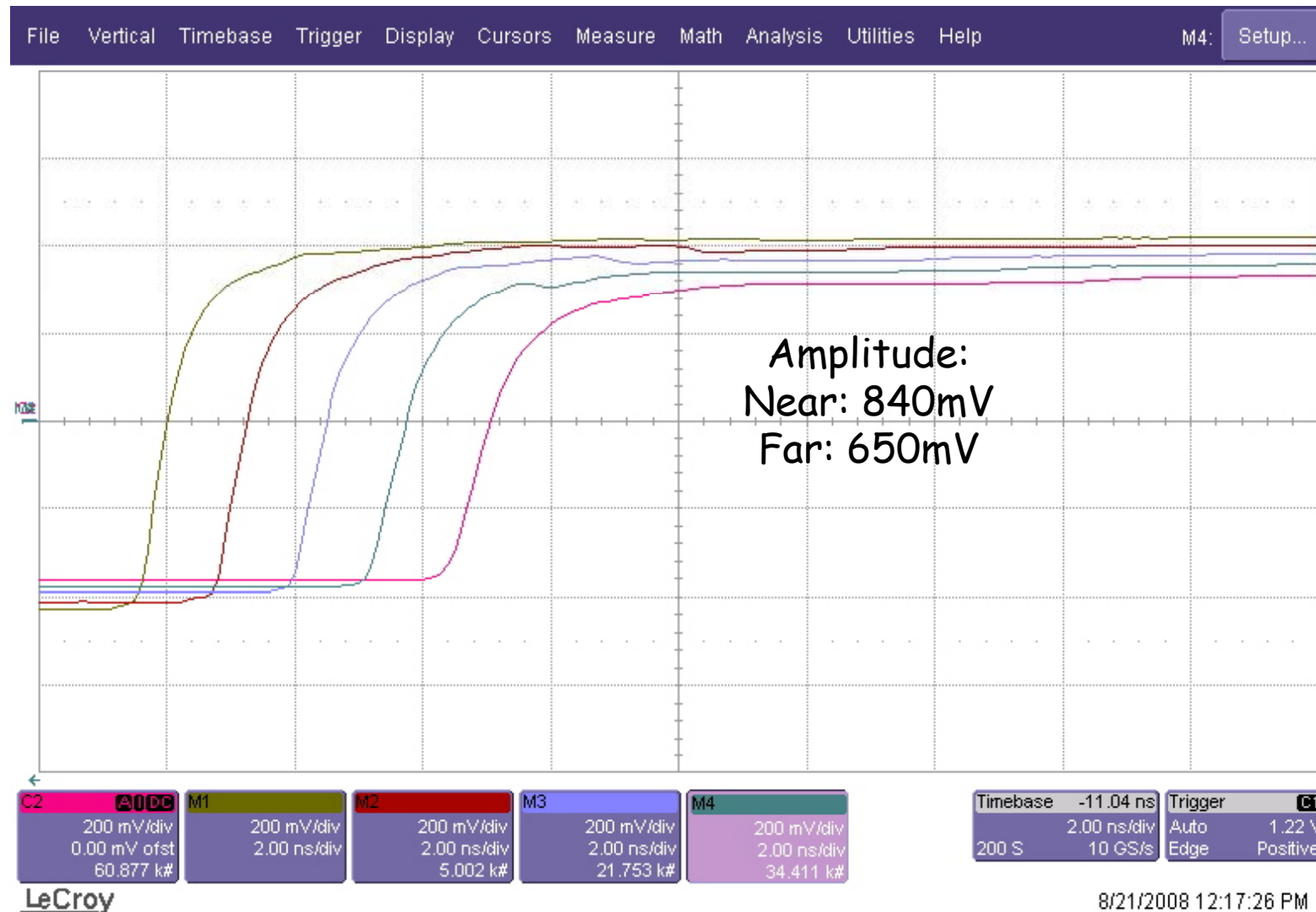


## ASU-Test\_2: Traces

Group	Pair Separation/ (Track & Gap)
A	1
B	1.5
C	2
D	3

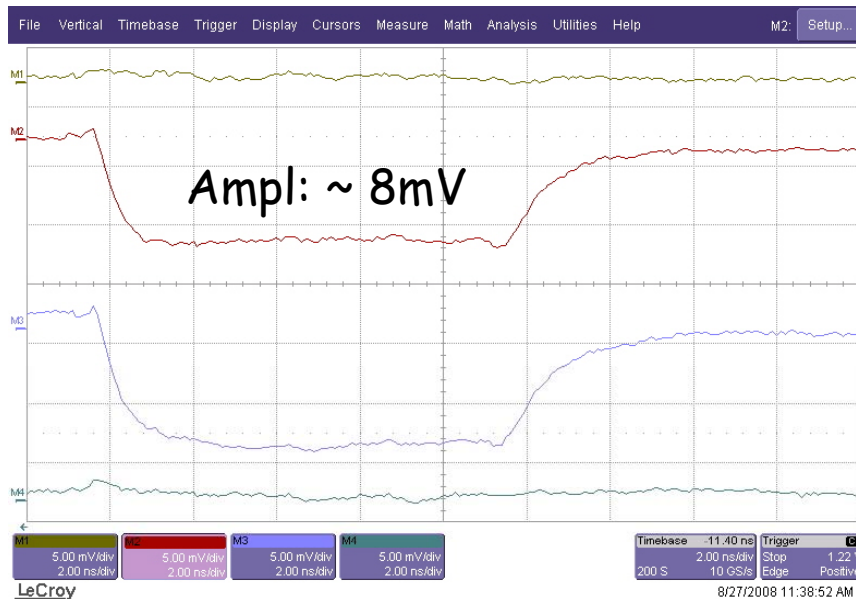
## ASU-Test\_2: Traces

# ECAL SLAB Interconnect - Crosstalk

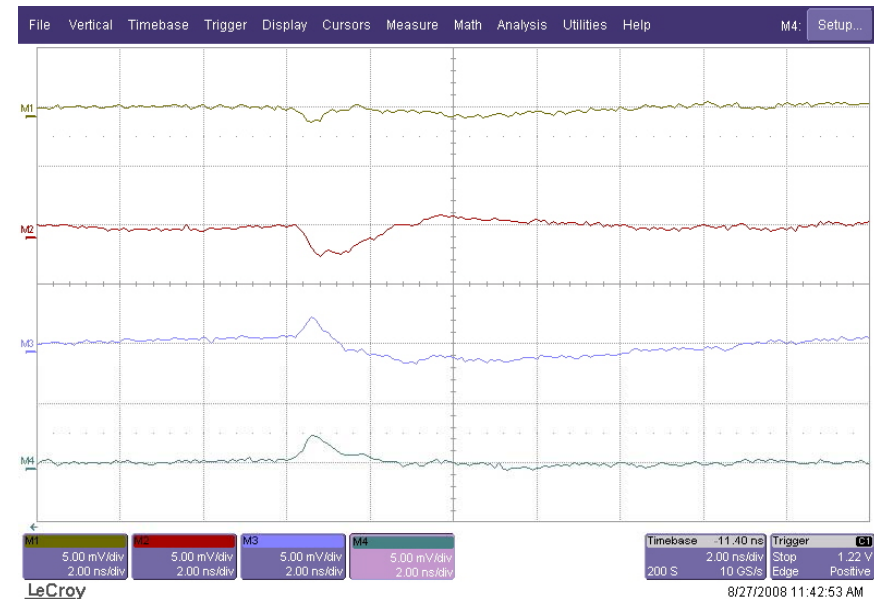


## ASU-Test\_2: Aggressor Signal Propagation (Pr2, Group A)

# ECAL SLAB Interconnect - Crosstalk



Driver End



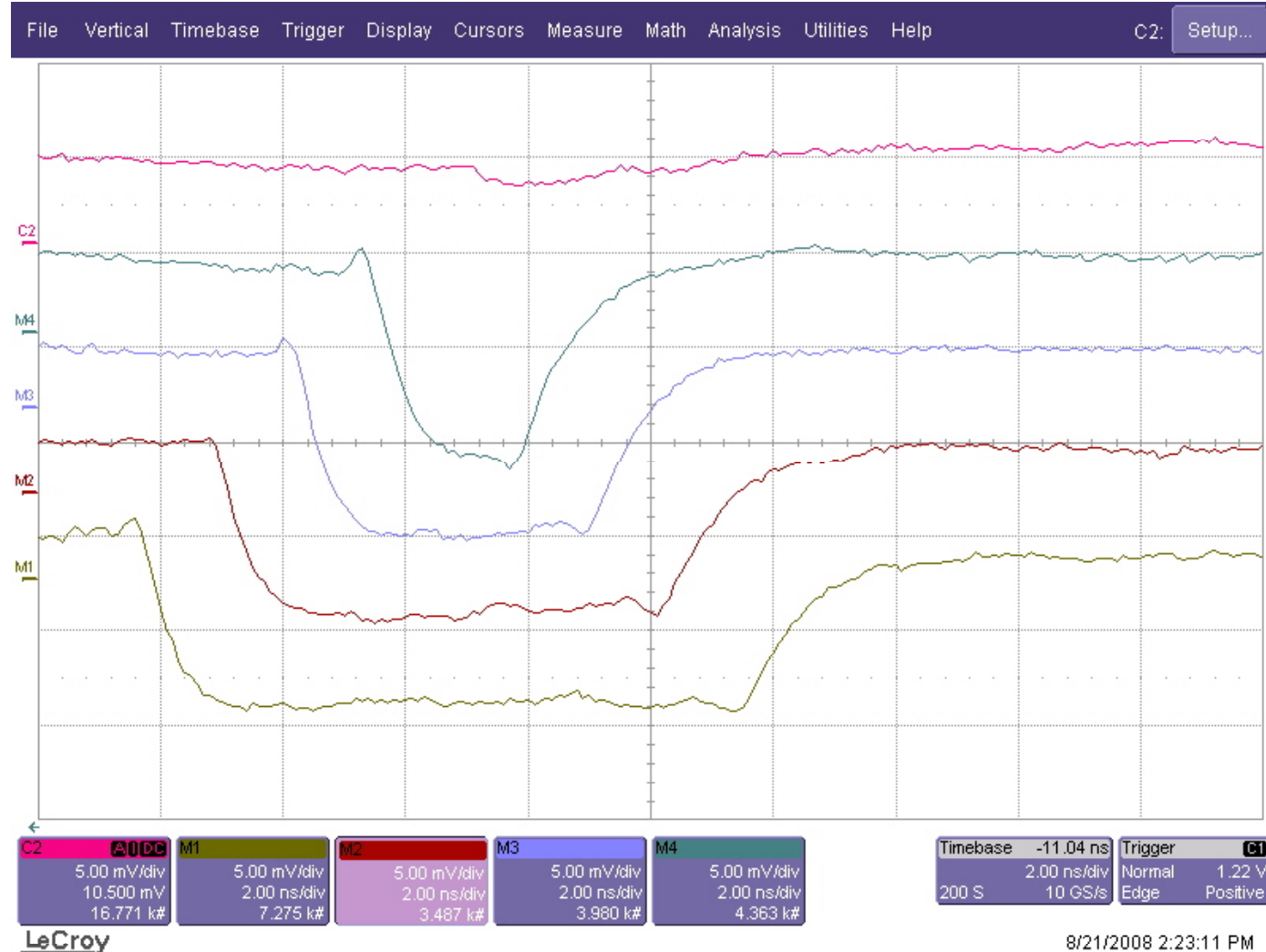
Far End

ASU-Test\_2: Victim Crosstalk (Prs 0,1,3,4, Group A)

# ECAL SLAB Interconnect - Crosstalk

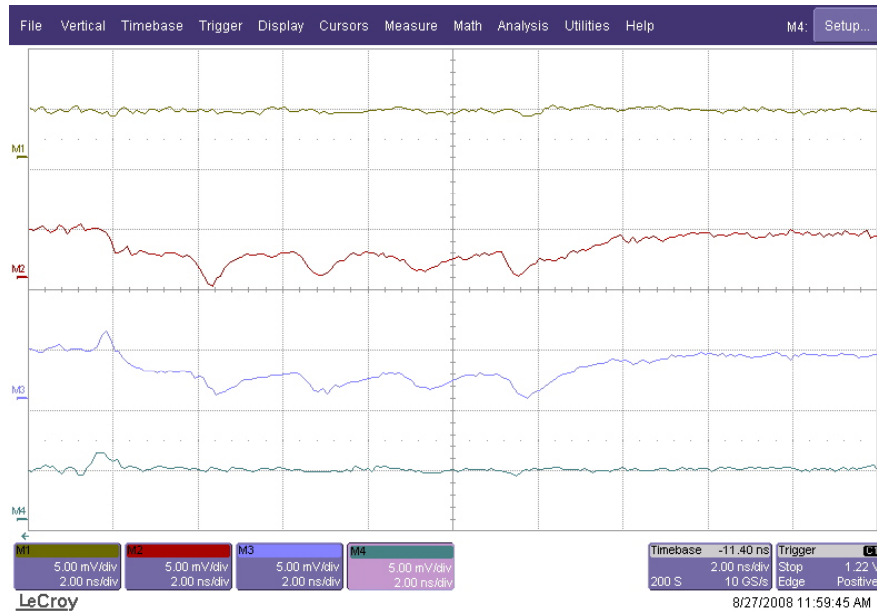
Far End

Near End

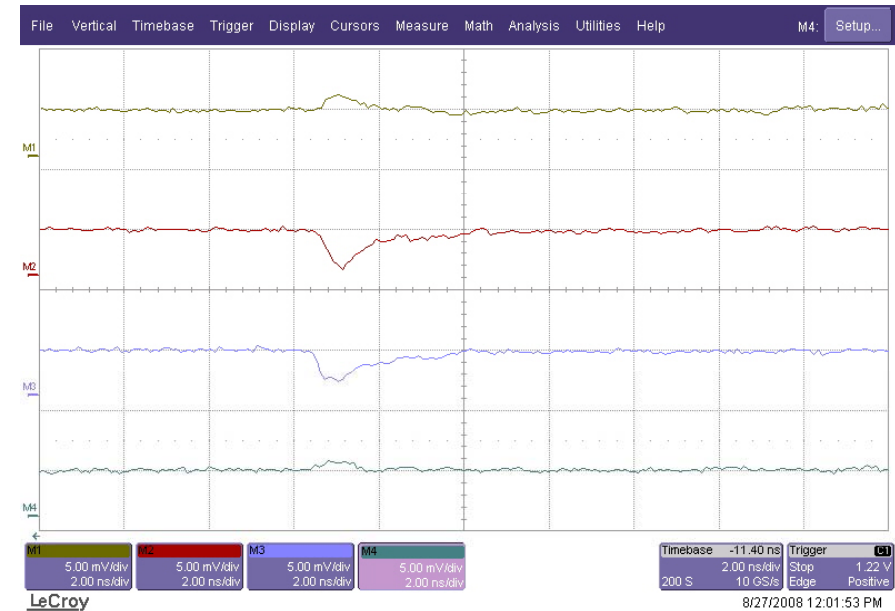


ASU-Test\_2: Victim Crosstalk Along Slab (Pr 1, Group A)

# ECAL SLAB Interconnect - Crosstalk



Driver End



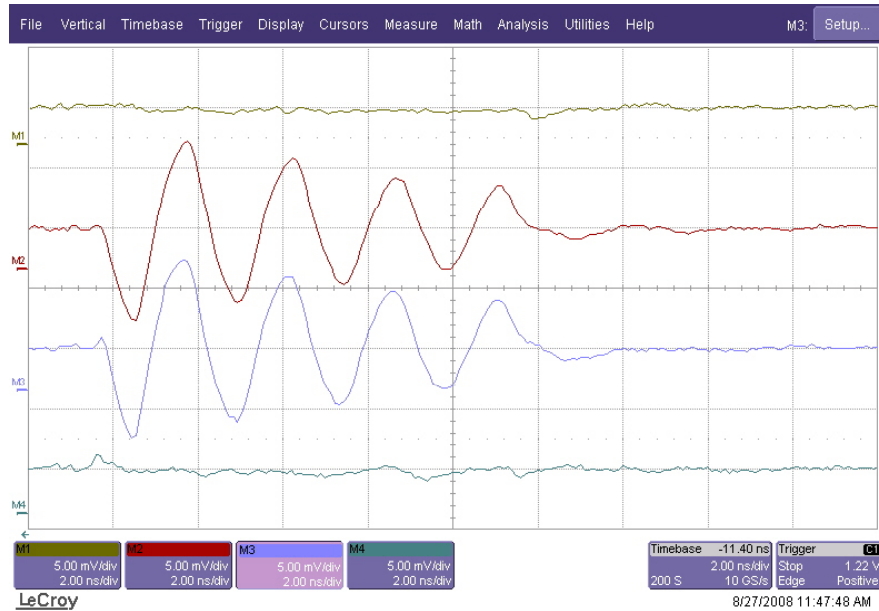
Far End

**Greater Pair Separation => Far Less Crosstalk**

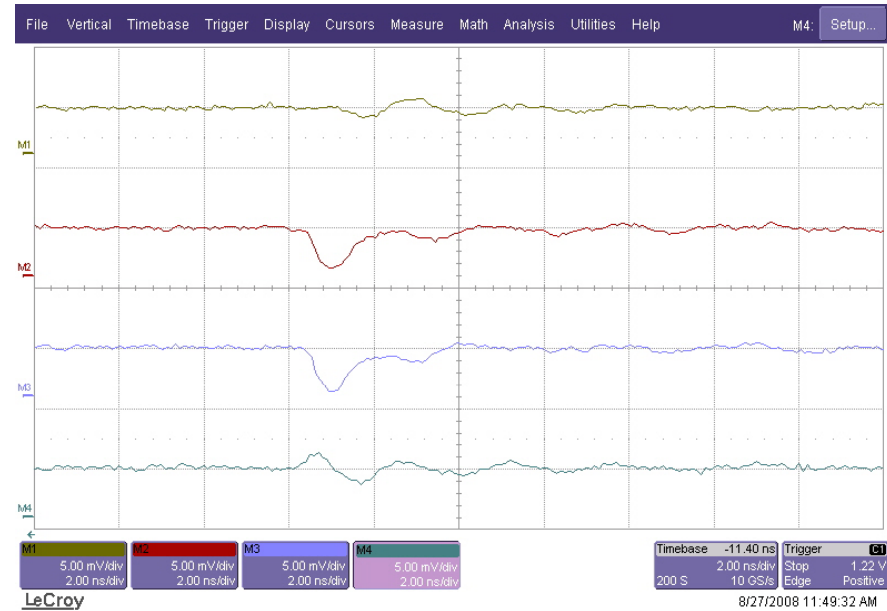
ASU-Test\_2: Victim Crosstalk (Prs 0,1,3,4, Group C)



# ECAL SLAB Interconnect - Crosstalk



Driver End

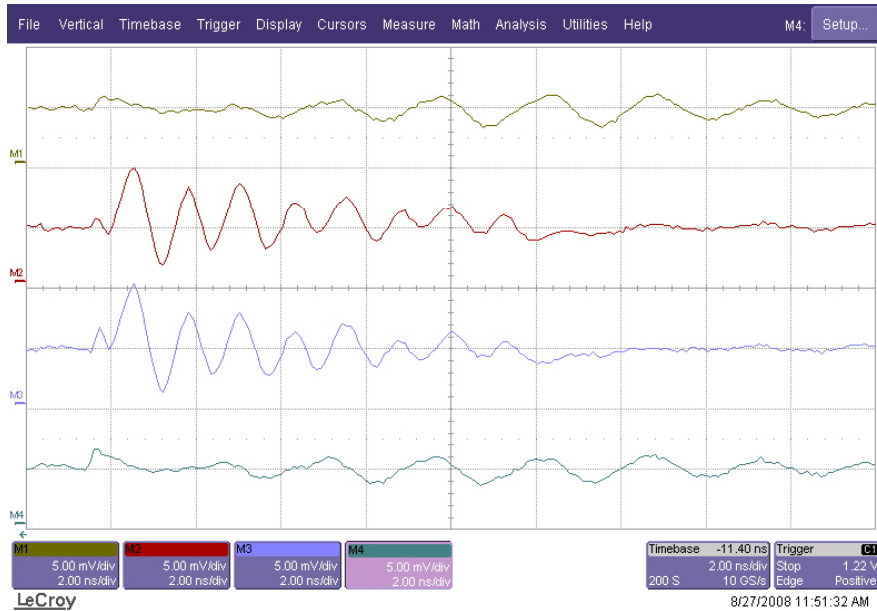


Far End

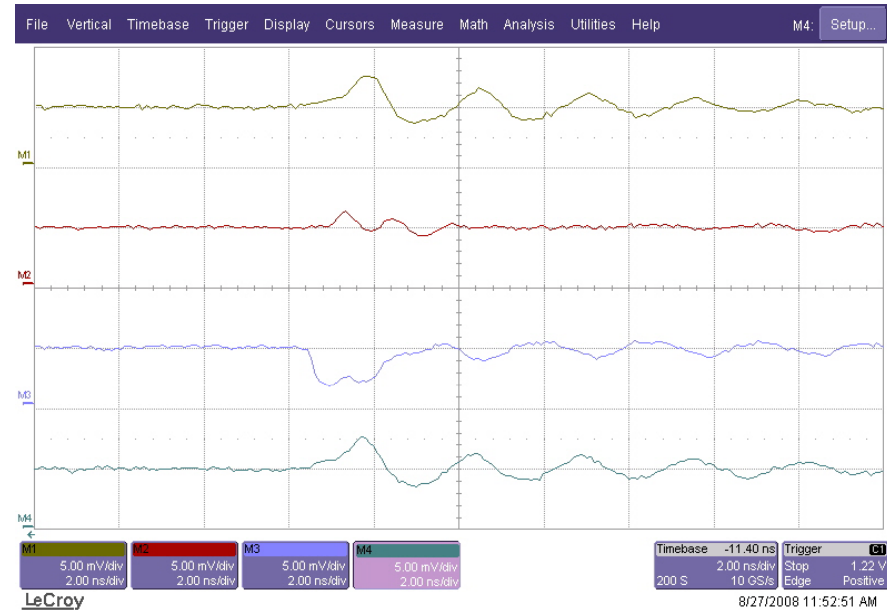
**"With Twists"**  
**Crosstalk alternates sign**

**ASU-Test\_2: Victim Crosstalk (Prs 5,6,8,9, Group A)**

# ECAL SLAB Interconnect - Crosstalk



Driver End



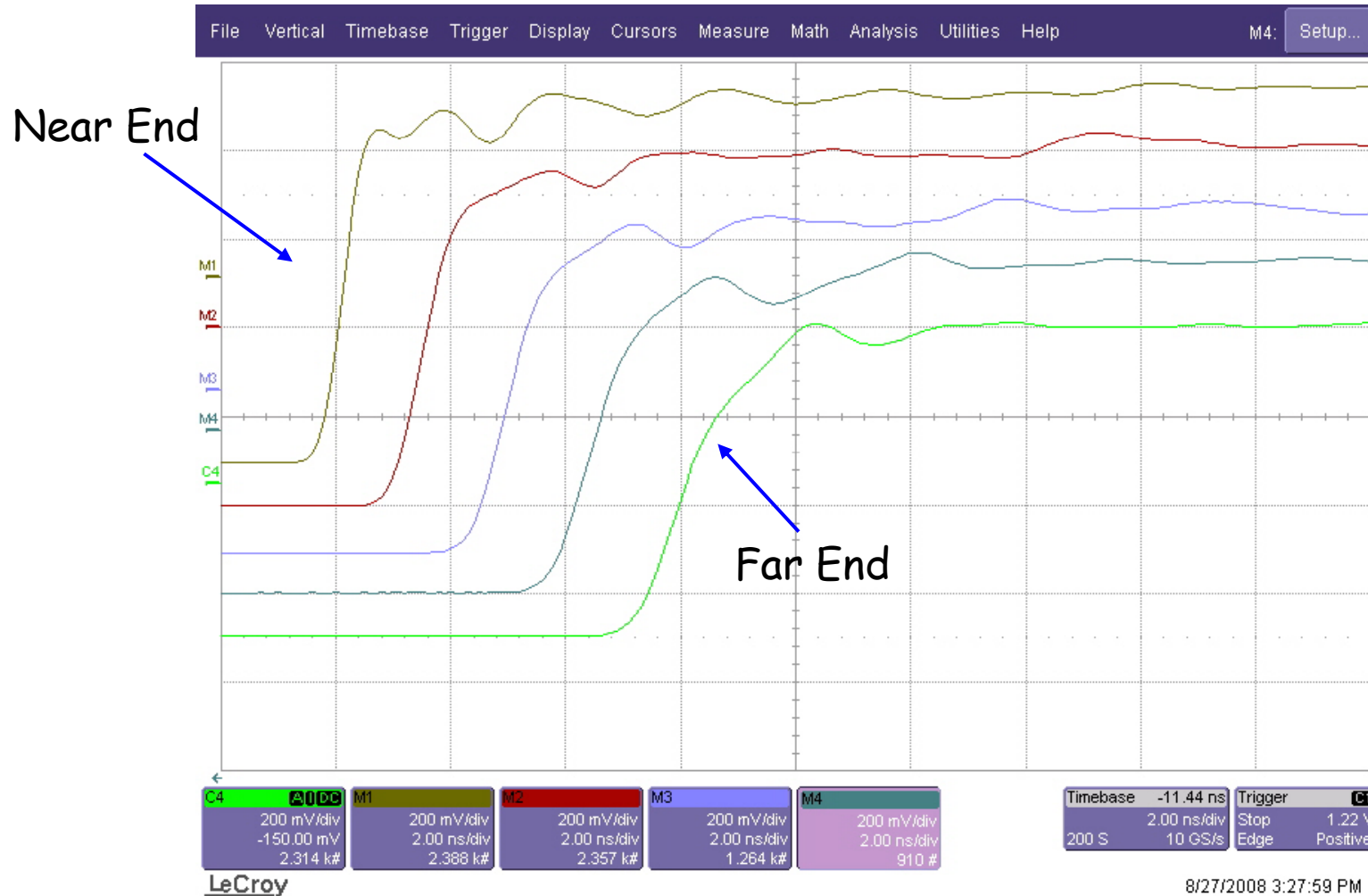
Far End

**"With Extra Twists"**

**Crosstalk alternates sign twice as fast**

ASU-Test\_2: Victim Crosstalk (Prs 10,11,13,14, Group A)

# ECAL SLAB Interconnect - Crosstalk



ASU-Test\_2: Propagation with Added 10pFs at ASU Joints (Pr 2, Group C)

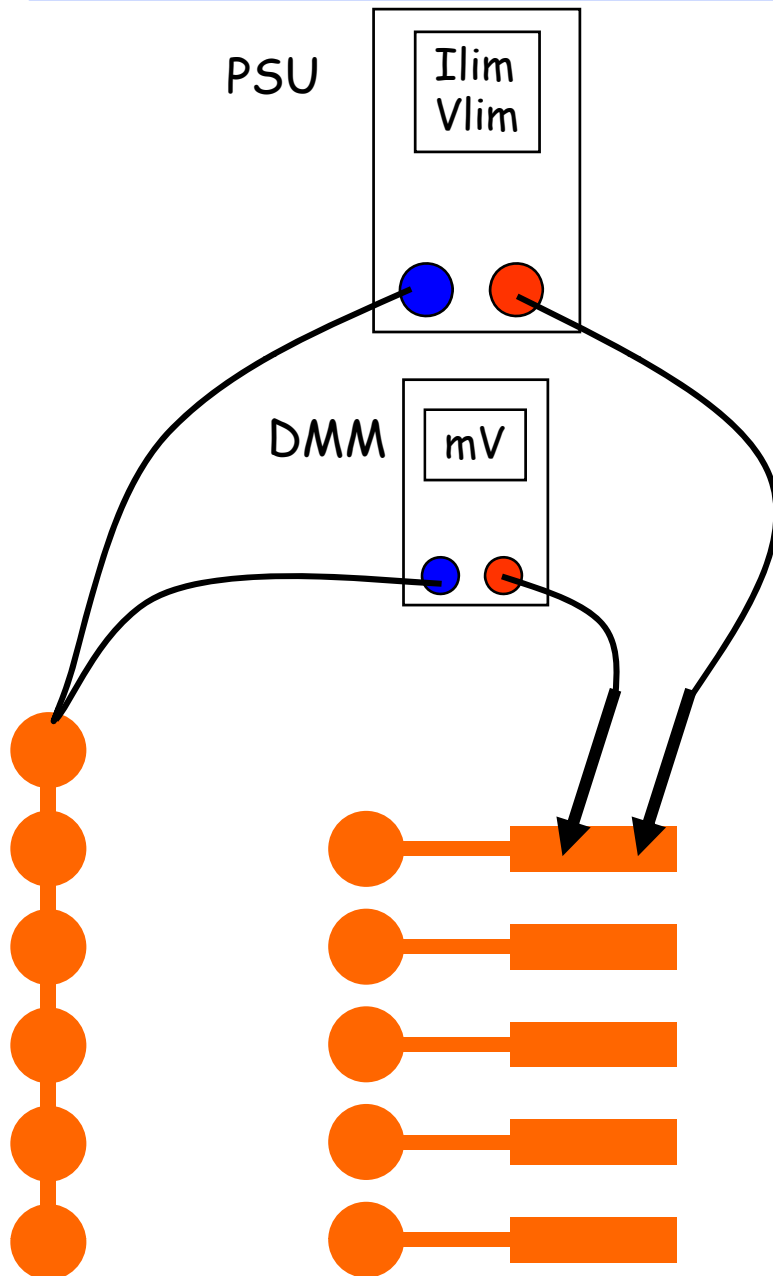
## Conclusions: for the 750mm Assembly

- Signal degradation and crosstalk look relatively small, even with closely spaced pairs (~10mV)
- Pair separation of 2 x Track & Gap reduces crosstalk dramatically (confirming folk lore)
- "Twisting" pairs doesn't really help
- Periodic capacitive loads do have a perceptible effect (~100mV) - this will have to be watched

- Marc Anduze provided a number of 300um 90x90 glass plates (plus some of 500um)
- We had 9 of them aluminised
- Manchester glued 2 of these to Gluetest PCBs
- We have made initial resistance measurements
- Plan is to subject these to the IR soldering process, and to re-check the resistances

- We find that glue joints are not simple!
- Ray Thompson of Manchester has written a very useful note on this
- We will use both leaded (183 deg) and Sn-Bi solder (150 deg)
- If these temperatures are a problem, it might push us to Laser Soldering

# ECAL SLAB Interconnect - GlueTest Initial



GlueTest - PCB #1

Connector #1						
I Lim(mA)	50	50	50	50	50	100
V Lim (V)	1	2	3	4	1	1
Finger						
0	9.2	9.2	9.2	9.2	9.1	18
1	9	9	9	9	9	18
2	9.6	9.6	9.6	9.6	9.6	19
3	9.1	9	9	9.1	9	18
4	1000	2000	3000	22	21	43
5	1000	114	66	18	17	35
6	1000	2000	3000	20	20	40
7	1000	2000	3000	23	23	46
8	1000	2000	3000	28	27	56
9	1000	160	18	19	19	38
10	1000	87	18	18	18	37
11	1000	2000	22	24	24	49
12	470	31	15	15	14	30
13	180	31	17	17	16	33
14	1000	2000	33	29	29	58
15	1000	2000	3000	22	22	44
16	1000	31	16	16	16	32
17	1000	2000	3000	18	19	38
18	120	27	28	16	16	33
19	1000	38	18	18	18	36
20	1000	2000	3000	18	18	36
21	1000	2000	3000	20	20	41
22	1000	2000	3000	18	17	35
23	1000	2000	15	15	15	30
24	1000	2000	19	19	19	39
25	215	124	49	40	39	78
26	1000	2000	23	16	16	33
27	1000	2000	34	24	24	49
28	1000	2000	20	21	21	42
29	12	12	12	12	12	24





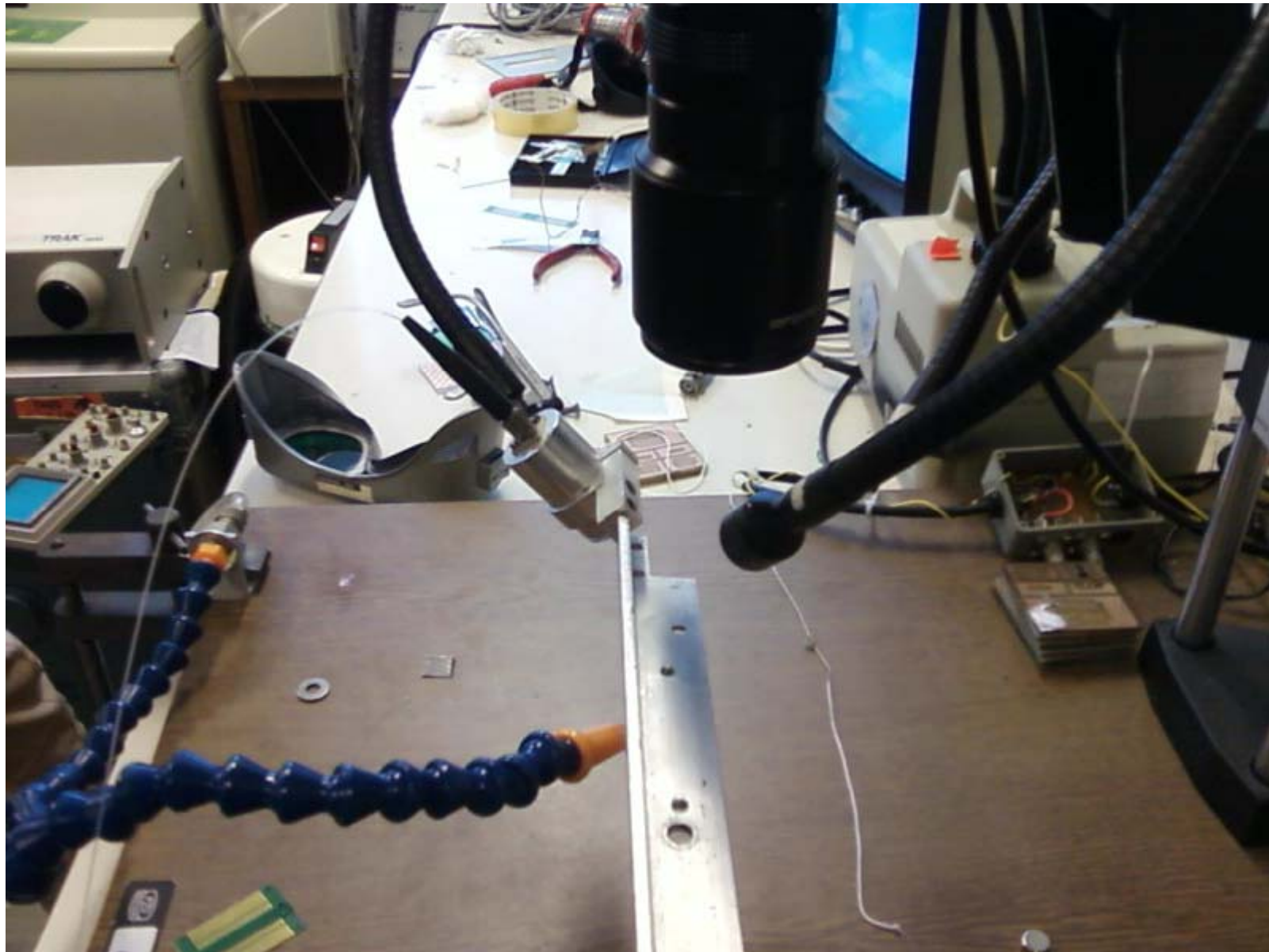
James Gilbert  
University of Hull  
Hull, UK

# ECAL SLAB Interconnect - Laser Soldering



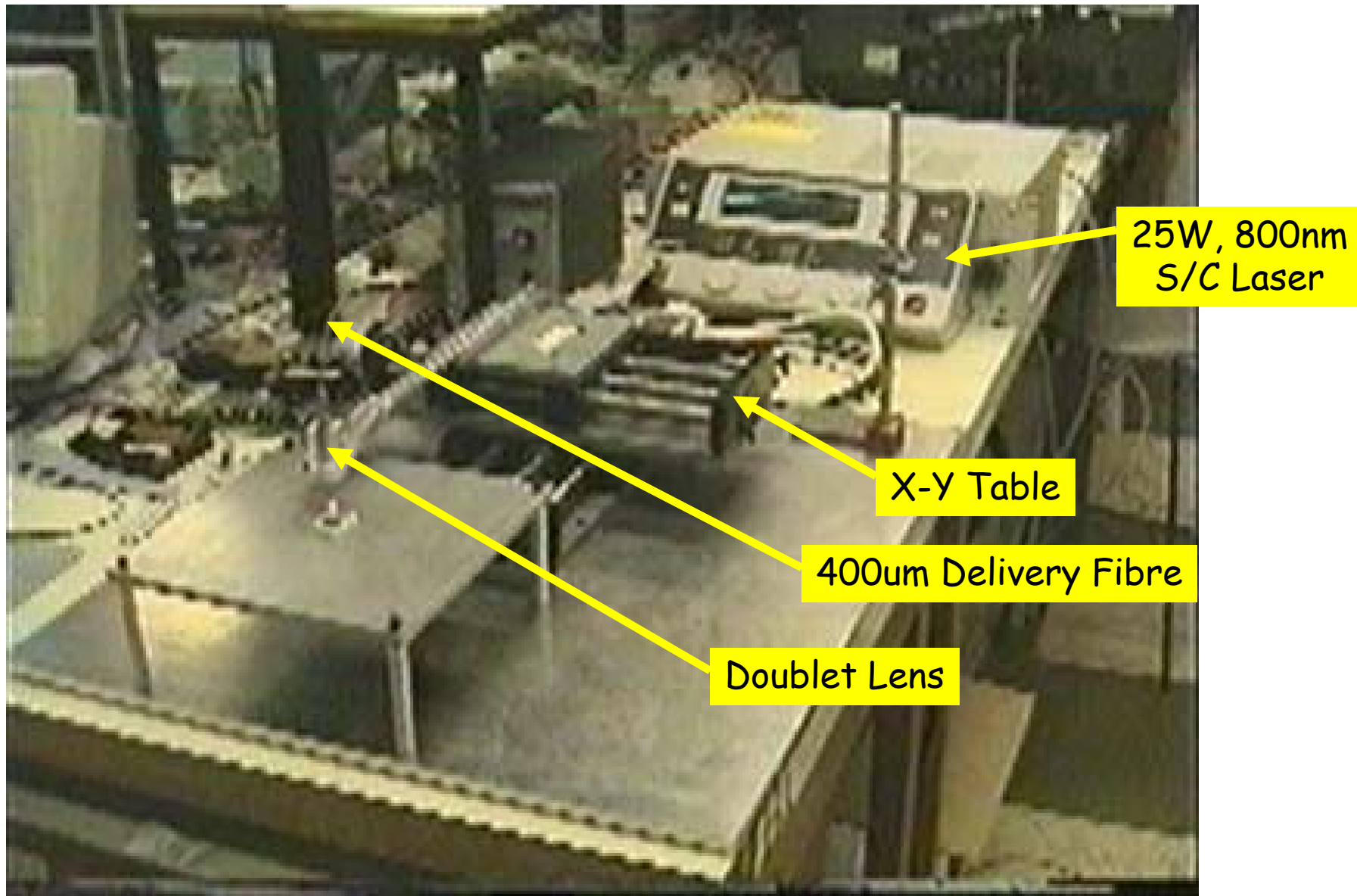
Maurice Goodrick & Bart Hommels , University of Cambridge

# ECAL SLAB Interconnect - **Laser Soldering**



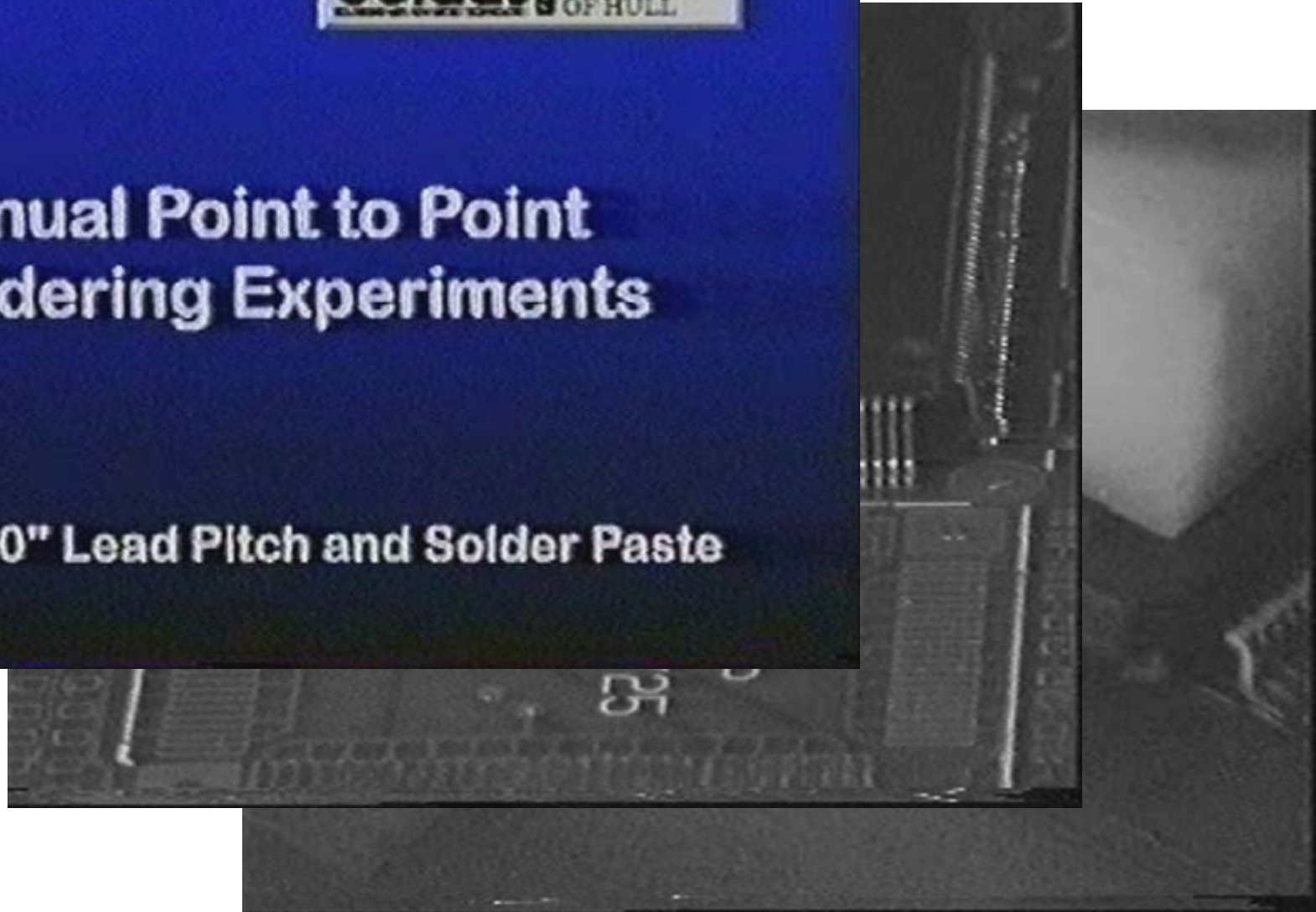
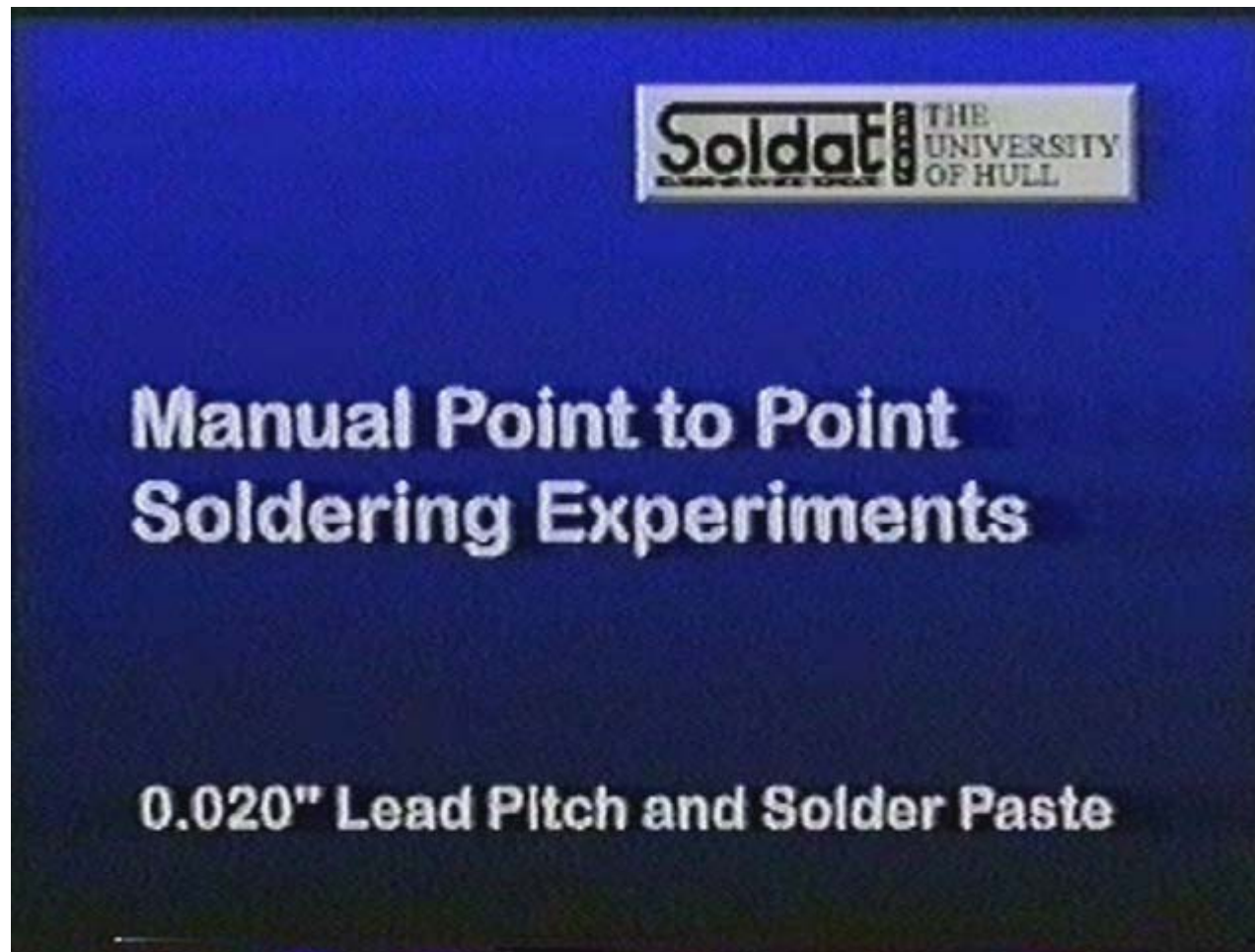
Maurice Goodrick & Bart Hommels , University of Cambridge

# ECAL SLAB Interconnect - Laser Soldering





# ECAL SLAB Interconnect - **Laser Soldering**



## Laser Soldering: Conclusions

- Promises low damage
- ~ 600 Euro/W: might need 10 - 25 W, so > 6000 Euro for laser
- Possibly going to be a bit slow
- Hull willing to do initial trials F.O.C.